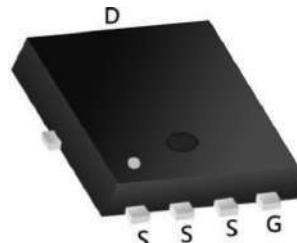


N-Ch 30V Fast Switching MOSFETs

Features:

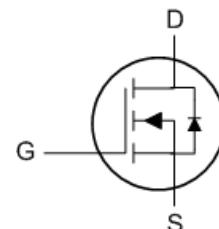
- * 100% UIS Tested
- * Advanced Trench Technology
- * High Current Capability
- * RoHS and Halogen-Free Compliant



PRPAK5X6 Pin Configuration

Applications:

- Power Management in Desktop Computer
- DC/DC Converters



Product Summary

BVDSS	RDS(on)	ID
30V	2.0mΩ	110A

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _c =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	110	A
I _D @T _c =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	71	A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	24.6	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	19.7	A
I _{DM}	Pulsed Drain Current ²	400	A
EAS	Single Pulse Avalanche Energy ³	204	mJ
I _{AS}	Avalanche Current	64	A
P _D @T _c =25°C	Total Power Dissipation ⁴	52	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2.5	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	50	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	2.4	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$	30	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=15\text{A}$	---	1.6	2.0	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=15\text{A}$	---	2.7	3.5	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.2	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.6	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=15\text{A}$	---	20.4	---	nC
Q_{gs}	Gate-Source Charge		---	6.7	---	
Q_{gd}	Gate-Drain Charge		---	8.6	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_g=3.3\Omega$, $I_{\text{D}}=1\text{A}$	---	12	---	ns
T_r	Rise Time		---	25	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	39	---	
T_f	Fall Time		---	23	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2235	---	pF
C_{oss}	Output Capacitance		---	956	---	
C_{rss}	Reverse Transfer Capacitance		---	156	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,6}	$V_G=V_D=0\text{V}$, Force Current	---	---	100	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	1.2	V
T_{rr}	Reverse Recovery Time	$I_F=15\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^{\circ}\text{C}$	---	62.2	---	nS
Q_{rr}	Reverse Recovery Charge		---	46.4	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=52\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 100A.

Typical Characteristics

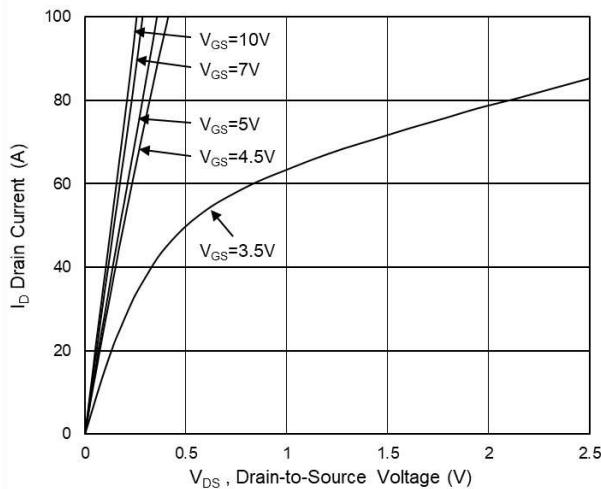


Fig.1 Typical Output Characteristics

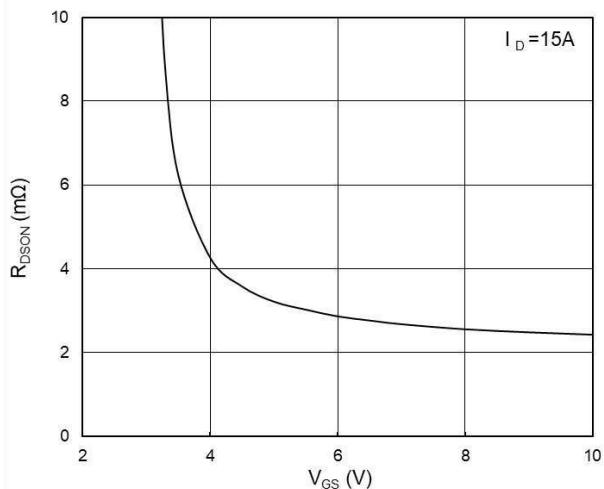


Fig.2 On-Resistance vs G-S Voltage

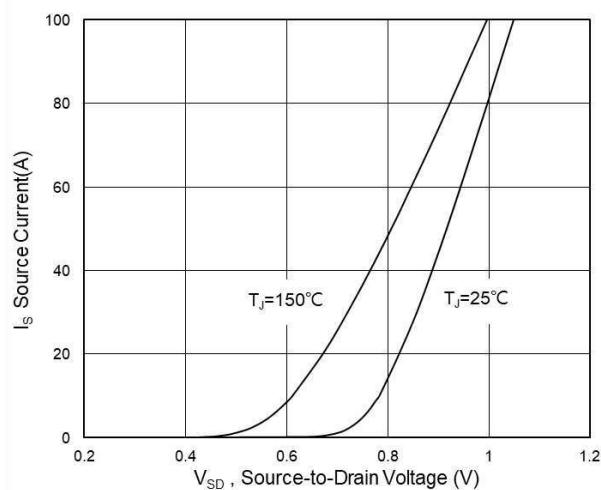


Fig.3 Source Drain Forward Characteristics

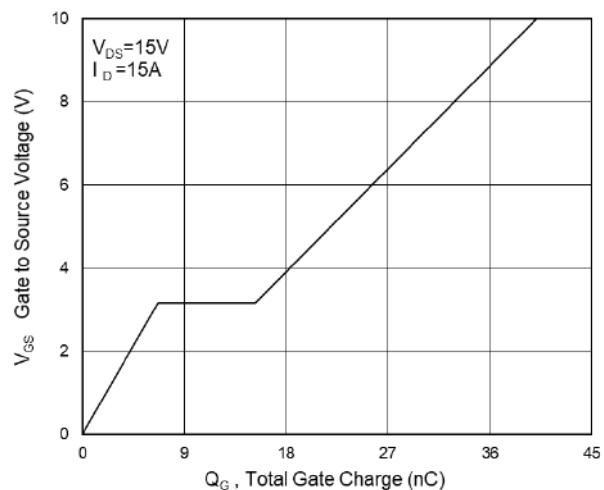


Fig.4 Gate-Charge Characteristics

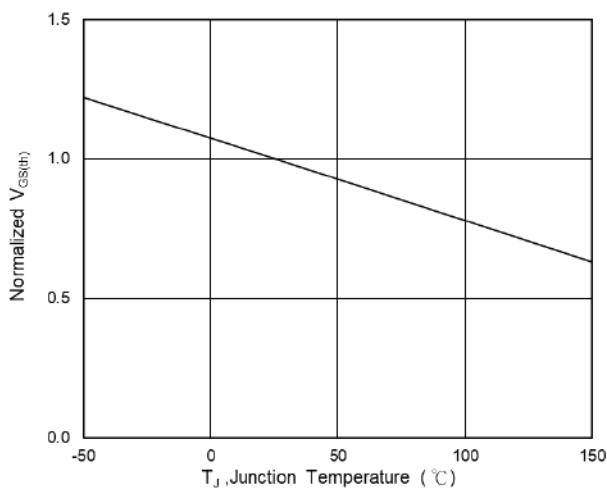


Fig.5 Normalized V_{GS(th)} vs T_J

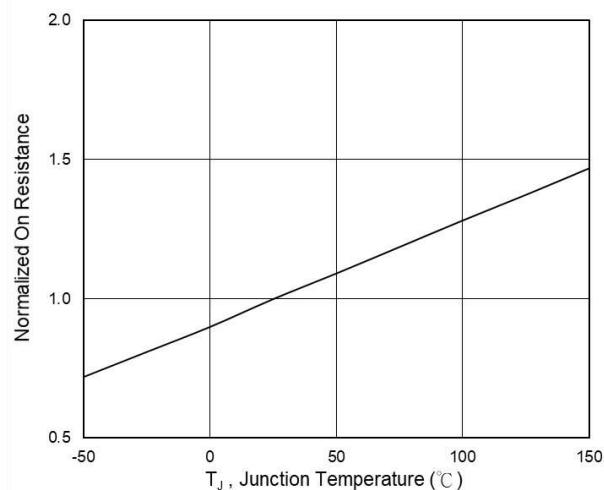


Fig.6 Normalized R_{DSON} vs T_J

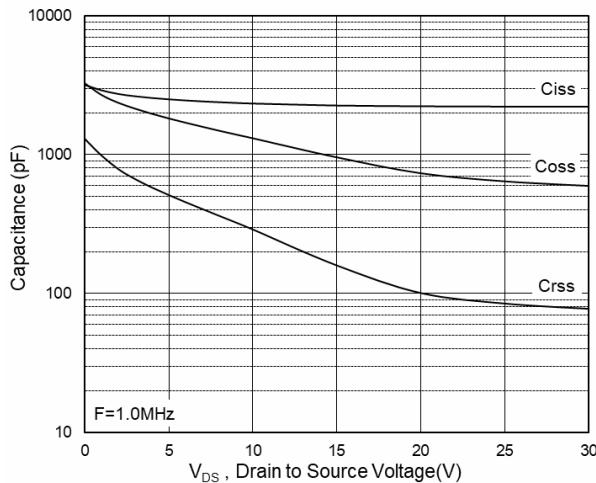


Fig.7 Capacitance

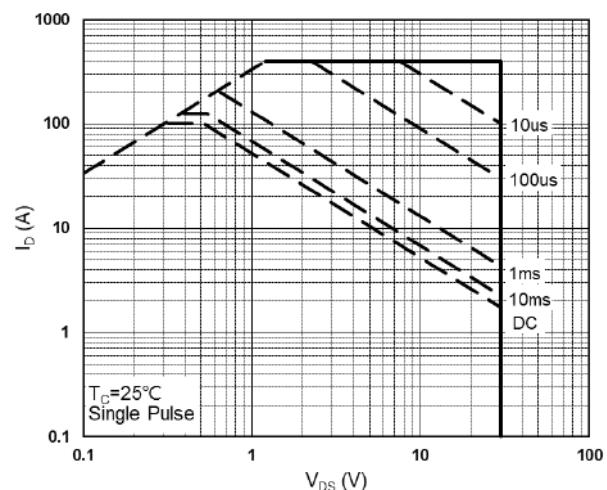


Fig.8 Safe Operating Area

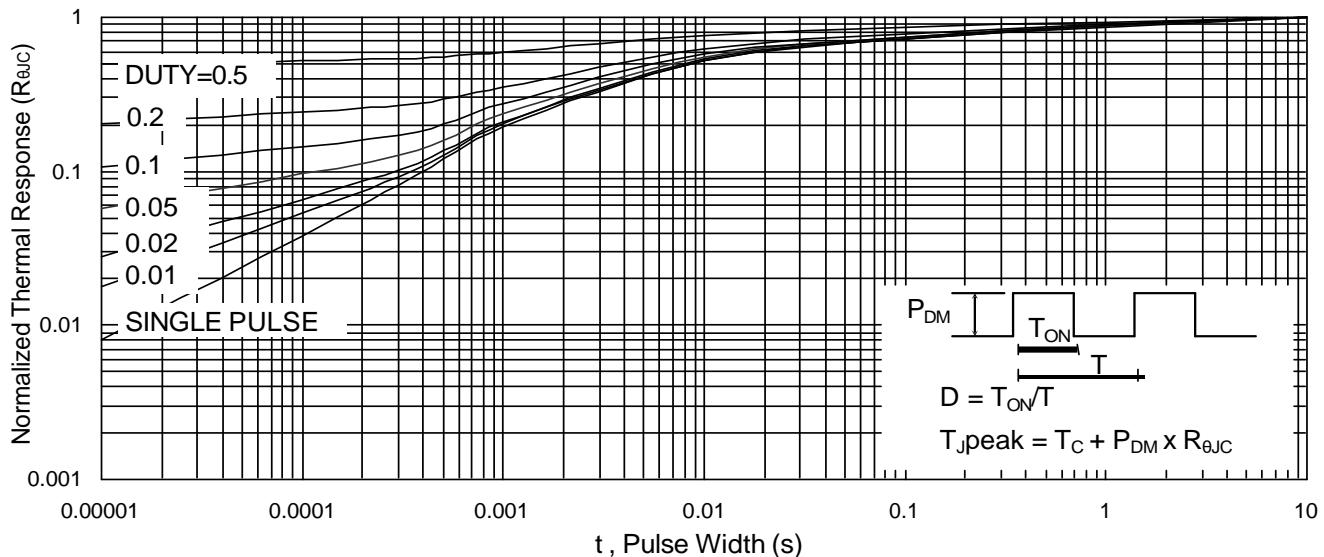


Fig.9 Normalized Maximum Transient Thermal Impedance

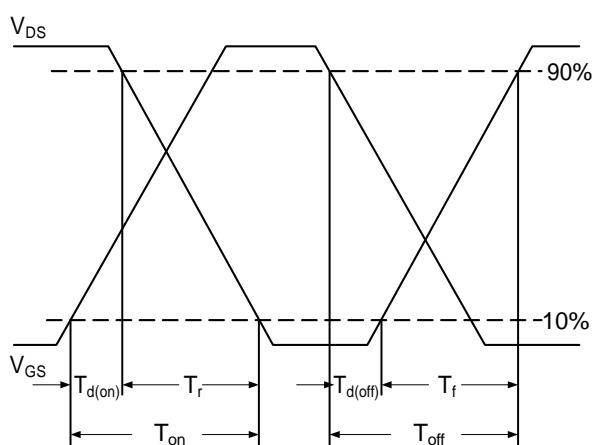


Fig.10 Switching Time Waveform

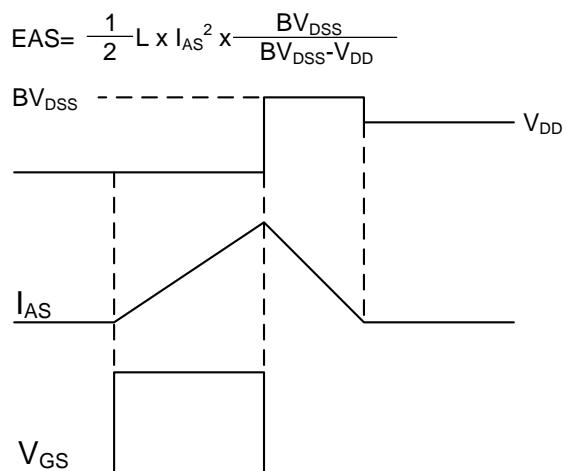


Fig.11 Unclamped Inductive Switching Waveform